IEEE Symposium on Low-Power and High-Speed Chips and Systems

COOL Chips 26

Takeda Hall, The University of Tokyo, Bunkyo-ku, Tokyo, Japan

April 19 – 21, 2023

CALL FOR CONTRIBUTIONS

COOL Chips is an International Symposium initiated in 1998 to present advancement of low-power and high-speed chips and systems. The symposium covers leading-edge technologies in all areas of microprocessors and their applications. The COOL Chips 26 is to be held in Tokyo on April 19-21, 2023, and is targeted at the architecture, design and implementation of chips and systems with special emphasis on the areas listed below. All papers are published online via IEEE Xplore. Especially, selected papers are encouraged to submit to the IEEE Micro and the special section in the IEICE Transactions on Electronics.

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Contributions are solicited in the following areas:

- **Low Power-High Performance Processors and Systems for -**
  AI, IoT, Multimedia, Digital Consumer Electronics, Mobile, Graphics, Encryption, Robotics, Automotive, Networking, Medical, Healthcare, and Biometrics.
- **Novel Architectures and Schemes for -**
  Single Core, Multi/Many-Core, NoC, Embedded Systems, Reconfigurable Computing, Grid, Ubiquitous, Dependable Computing, GALS and 3D Integration
- **Cool Software including - Parallel Schedulers, Embedded Real-time Operating System, Binary Translations, Compiler Issues and Low Power Application Techniques.**

Proposals should consist of a title, the name, job title, address, phone number and e-mail address of the presenter in a full paper format (6 pages) or an extended abstract format (up to 3 pages) describing the product or topic to be presented. The status of the product or topic should precisely be described. Proposals will be selected by the program committee's evaluation of interest to the audience. Submission should be made through website. Detailed instructions are in author's kit obtained from our Web-site.

Author Schedule:	**February 28, 2023**	**Paper / Extended Abstract Submission (Web-site)**
	March 17, 2023	**Acceptance Notified (by e-mail)**
	March 31, 2023	**Final Manuscript Submission**

You are also invited to submit proposals for poster sessions. Submission should be made through website. Detailed instructions are in author's kit obtained from our Web-site.

Author Schedule:	**March 24, 2023**	**Poster Abstract Submission (Web-site)**
	March 27, 2023	**Poster Acceptance Notified (by e-mail)**

For more information, please visit our Web-site <**https://www.coolchips.org/**>.
For any questions, please contact the Secretariat <**cool_26@coolchips.org**>.

Sponsored by the Technical Committees on Microprocessors and Microcomputers and Computer Architecture of the IEEE Computer Society. In cooperation with the IEICE Electronics Society and IPSJ .

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(basically in alphabetical order) **(As of February 28, 2023)**